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(54) Title: SUB-PAD FORMATION UTILIZING UV-CURABLE FORMULATION

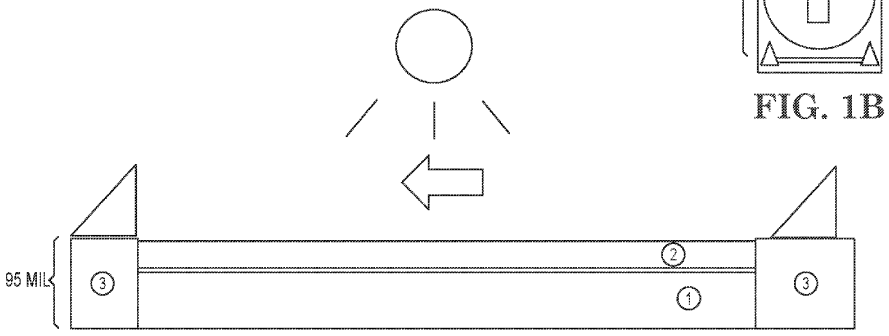


FIG. 1B

FIG. 1A

(57) Abstract: The disclosure provides a UV-cured sub-pad for chemical-mechanical planarization comprising (a) a (meth)acrylate monomer unit and (b) an oligomer unit selected from a difunctional (meth)acrylatecapped polyether urethane oligomer unit, a difunctional (meth)acrylate-capped polyester urethane oligomer unit, a difunctional (meth)acrylate-capped urethane oligomer unit, and a combination thereof. The disclosure also provides a polishing pad for chemical-mechanical planarization comprising a top sheet and a UV-cured sub-pad, a method of preparing the polishing pad, and an apparatus for performing the method of preparing the polishing pad for chemical-mechanical planarization.

[Continued on next page]

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